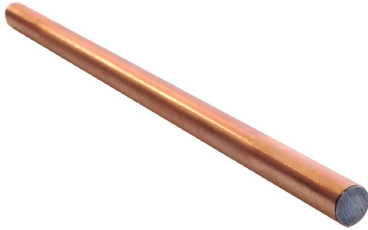


## Cooling Pins - Standard

- High speed heat transfer device
- Uniform Cooling Improves Part Quality
- Maximizes heat transfer efficiency
- Designed to be installed with PCS' Heat Transfer Compound (Paste).
- Mating hole in core should be drilled .003" - .004" larger than actual O.D. of pin.



Cooling Pins are high speed heat transfer devices capable of conducting heat energy over 10,000 times faster than copper, thus cooling molds faster and reducing cycle time. Cooling Pins are used to heat or cool cores, slides and inserts in thermoset and thermoplastic molds. This isothermic device allows for optimal heat transfer rates within cores and slides.

SPECIFICATIONS	
Material Type	Heat Pipe
Unit of Measure	Inch

CATALOG NO.	DIA.		OVERALL LENGTH																
	INCH	DEC.	2	2-1/2	3	3-1/2	4	4-1/2	5	5-1/2	6	6-1/2	7	7-1/2	8	8-1/2	9	9-1/2	10
AT7-	3/32	.094	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT9-	1/8	.125	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT11-	5/32	.156	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT13-	3/16	.187	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT15-	7/32	.219	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT17-	1/4	.250	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT21-	5/16	.312	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT25-	3/8	.375	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT33-	1/2	.500	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•
AT37-	5/8	.625	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•	•

Add length to end of catalog number (i.e. AT7-2)

## Cooling Pins - Heat Transfer Compound



- Used exclusively with Cooling Pins
- Maximizes heat transfer efficiency

Heat Transfer Compound must be used with both inch and metric cooling pins. The compound increases thermal conductivity by filling in the air gaps present between the cooling pin and any components.

SPECIFICATIONS	
Material Type	Thermal Paste

CATALOG NO.	VOLUME
ATP-1	5 GR.
ATP-4	4 OZ.
ATP-8	8 OZ.
ATP-16	16 OZ.